

Variant: 001
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PMP15022 REV E1 Bill of Materials

Item #	Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
1	C1, C2, C3, C4, C10, C11	6	10uF	GRM31CR61H106KA12L	MuRata	CAP, CERM, 10 µF, 50 V, +/- 10%, X5R, 1206	1206
2	C5, C8	2	0.1uF	GCM188R71C104KA37J	MuRata	CAP, CERM, 0.1 µF, 16 V, +/- 10%, X7R, 0603_095	0603_095
3	C6	1	470pF	GCM1885C1H471JA16D	MuRata	CAP, CERM, 470 pF, 50 V, +/- 5%, C0G/NP0, 0603_095	0603_095
4	C7	1	1uF	GCM188R71C105KA64D	MuRata	CAP, CERM, 1 µF, 16 V, +/- 10%, X7R, 0603_095	0603_095
5	C9	1	1uF	GRM31CR72A105KA01L	MuRata	CAP, CERM, 1 µF, 100 V, +/- 10%, X7R, 1206	1206
6	C12, C13	2	0.1uF	GRM188R72A104KA35D	MuRata	CAP, CERM, 0.1 µF, 100 V, +/- 10%, X7R, 0603	0603
7	D1	1	60V	RB058L-60TE25	Rohm	Diode, Schottky, 60 V, 3 A, AEC-Q101, SMA	SMA
8	D4, D6	2	100V	MMSD4148T1G	ON Semiconductor	Diode, Switching, 100 V, 0.2 A, SOD-123	SOD-123
9	L1, L2	2	10uH	XAL4040-103MEB	Coilcraft	Inductor, Shielded, Composite, 10 µH, 3 A, 0.084 ohm, SMD	4.0x4.1x4.0mm
10	Q1	1	20V	FDC6305N	Fairchild Semiconductor	MOSFET, N-CH, 20 V, 2.7 A, SSOT-6	SSOT-6
11	R1, R4	2	19.1k	RC0603FR-0719K1L	Yageo America	RES, 19.1 k, 1%, 0.1 W, 0603	0603
12	R2	1	0	CRCW06030000Z0EA	Vishay-Dale	RES, 0, 5%, 0.1 W, 0603	0603
13	R3, R10	2	100k	CRCW0603100KFKEA	Vishay-Dale	RES, 100 k, 1%, 0.1 W, 0603	0603
14	R5	1	0.165	PT1206FR-070R165L	Yageo America	RES, 0.165, 1%, 0.25 W, 1206	1206
15	R6, R8, R9	3	10.0k	CRCW060310K0FKEA	Vishay-Dale	RES, 10.0 k, 1%, 0.1 W, 0603	0603
16	R7	1	110k	CRCW0603110KFKEA	Vishay-Dale	RES, 110 k, 1%, 0.1 W, 0603	0603
17	U1	1		TPS92515DGQR	Texas Instruments	2-A, Buck LED Driver with Integrated N-channel FET, High-Side Current Sense, and Shunt FET PWM Dimming Capability, DGQ0010E (VSSOP-10)	DGQ0010E
18	U2	1		SN74LVC1G17DCKR	Texas Instruments	SINGLE SCHMITT-TRIGGER BUFFER, DCK0005A (SOT-5)	DCK0005A

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